ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES INTERNAL MALECTRONICS INDUSTRIES INTERNAL International and Pan-American co	ourn, Illinois, All rights reserved u	nder both This docum level parts, t	ent is a declara the declaration	tion of the substa encompasses all	ances within the lower level mate	nanufacturer list rials for which t	ed item. Note: he manufacture	if the item is an as er has engineering	sembly with lower responsibility.		
IPC Web Site for Information on I http://www.ipc.org/IPC-175x	PC-1752 Standard	Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and M				d Mfg Informa	ation			
Supplier Information											
Company name*	e* Company unique ID			Unique ID Authority				Response Date*			
onsemi								2025-06-06			
Contact Name	Title - Contact		Phone - Contact*			Ema	Email - Contact*				
Product-Env-Stewards	Product Enviro Compliance		NA			Pro	Product-Env-Stewards@onsemi.com				
Authorized Representative*	Title - Representative		Phone - Representative*			Ema	Email - Representative*				
Product-Env-Stewards Product Enviro Compliance			NA			Pro	Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr Item	Number Mfr Item Name	Mfr Item Name		e Version	Manufacturi	Manufacturing Site		UOM	Unit Type		
NCP115	ASN150T2G 300 mA CMOS L AD; TSOP5	ow Dropout Regulator 1V5	2025-06-06		CN1		13.65	mg	Each		
Manufacturing Proccess Information											
Terminal Plating / Grid Array Material	Ferminal Base Alloy J	-STD-020 MSL Rating	Peak Pro	Process Body Temperature Max Time at Peak		ne at Peak Temp	Temperature Number of Reflow Cycles		cles		
Matte Tin (Sn) - annealed CU Alloy 1		l	260	С	30	se	econds 3				
Comments											
level 1 - maximum time at peak temperature during so	Idering is 10-30 seconds										
For more information regarding material composition	please refer to page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DIP).								
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted				
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all				
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the				
Supplier Digital Signature Ra	stislav Drska	Le							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.12	mg	Supplier	Silicon (Si)	7440-21-3		0.12	mg
Lead Frame 5.7	5.78	mg	Supplier	Silver (Ag)	7440-22-4		0.526	mg
			В	Nickel (Ni)	7440-02-0		2.127	mg
			Supplier	Iron (Fe)	7439-89-6		2.9189	mg
			Supplier	Copper (Cu)	7440-50-8		0.2081	mg
Mold Compound-Black 7.34	7.34	mg		Epoxy resin	proprietary data		0.367	mg
			Supplier	Phenolic Resin	Proprietary Data		0.367	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.1468	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0367	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.4225	mg
Plating	0.39	mg	Supplier	Tin (Sn)	7440-31-5		0.39	mg
Wire Bond - Cu	0.02	mg	Supplier	Copper (Cu)	7440-50-8		0.02	mg